

Manufacturing method and device for aluminum nitride particles

High production yield and extremely low energy consumption!

Overview

Aluminum nitride (AIN) is known to be used as a filler in the sealing resin of electronic components and semiconductors to efficiently dissipate the heat due to its high insulation and thermal conductivity, and can significantly improve their life. However, the shape of the AIN particles produced by sintering at high temperature for a long time is extremely irregular, and it is not possible to include a large amount of AIN particles uniformly in the sealing resin.

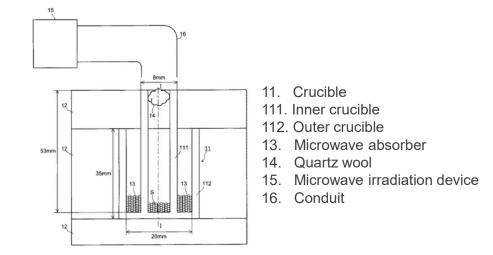
This invention is able to simply provide AIN particles with a new configuration that can be suitably used as a thermally conductive filler. In this invention, carbon & alumina particles are mixed and placed in a crucible, then irradiated by microwaves, contrary to conventional method where alumina particles are completely reduced by carbon particles.

Product Application

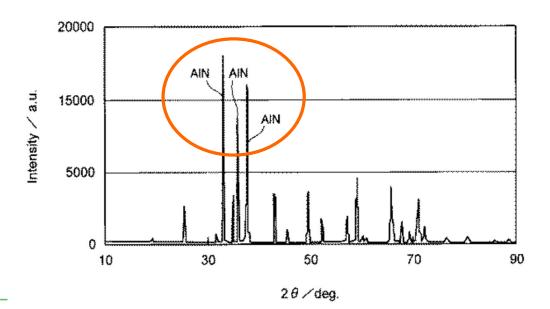
- Electronic device component
- Semiconductor chips

IP Data

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It is guessed that a surface layer consisting of AIN is formed



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